

16-BIT 2:1 MUX/DEMUX SWITCH

FEATURES:

- · Bus switches provide zero delay paths
- · Low switch on-resistance
- TTL-compatible input and output levels
- ESD > 2000V per MIL-STD-883, Method 3015; > 200V using machine model (C = 200pF, R = 0)
- · Hot insertion capability
- · Very low power dissipation
- · Available in SSOP and TSSOP packages

DESCRIPTION:

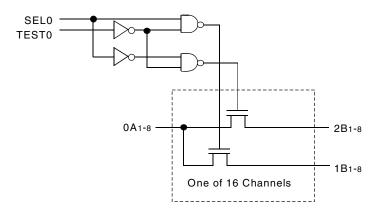
The FST163233 belongs to IDT's family of Bus switches. Bus switch devices perform the function of connecting or isolating two ports without providing any inherent current sink or source capability. Thus they generate little or no noise of their own while providing a low resistance path for an external driver. These devices connect input and output ports through an n-channel FET. When the gate-to-source junction of this FET is adequately forward-biased the device conducts and the resistance between input and output ports is small. Without adequate bias on the gate-to-source junction of the FET, the FET is turned off, therefore with no Vcc applied, the device has hot insertion capability.

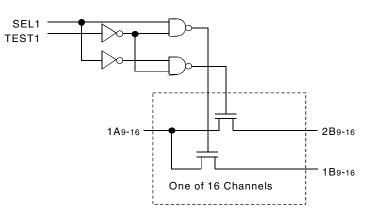
The low on-resistance and simplicity of the connection between input and output ports reduces the delay in this path to close to zero.

The FST163233 provides three 16-bit TTL-compatible ports that support 2:1 multiplexing. The SEL0,1 and TEST0,1 pins provide switch enable and mux select control as shown below.

The A port can be connected to port 1B or port 2B or both ports 1B and 2B.

FUNCTIONAL BLOCK DIAGRAM

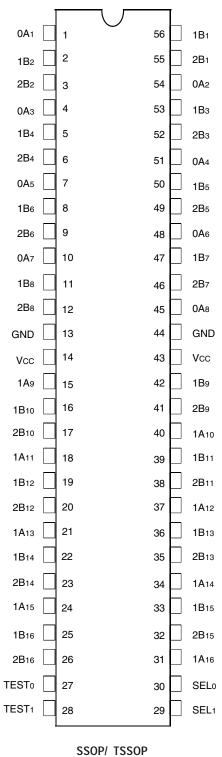




INDUSTRIAL TEMPERATURE RANGE

OCTOBER 2008

PINCONFIGURATION



TOP VIEW

INDUSTRIAL TEMPERATURE RANGE

ABSOLUTE MAXIMUM RATINGS⁽¹⁾

| Symbol | Description | Max | Unit |
|----------------------|--------------------------------------|-------------|------|
| VTERM ⁽²⁾ | Terminal Voltage with Respect to GND | –0.5 to +7 | V |
| Tstg | Storage Temperature | -65 to +150 | °C |
| Ιουτ | Maximum Continuous Channel Current | 128 | mA |

NOTES:

 Stresses greater than those listed under ABSOLUTE MAXIMUM RATINGS may cause permanent damage to the device. This is a stress rating only and functional operation of the device at these or any other conditions above those indicated in the operational sections of this specification is not implied. Exposure to absolute maximum rating conditions for extended periods may affect reliability.

2. Vcc, Control, and Switch terminals.

CAPACITANCE⁽¹⁾

| Symbol | Parameter | | Conditions ⁽²⁾ | Тур. | Unit |
|--------|-------------------------|--------|---------------------------|------|------|
| CIN | Control Input Capacitar | ice | | 6 | рF |
| Ci/o | Switch Input/Output | A Port | Switch Off | 17 | рF |
| | Capacitance | B Port | Switch Off | 12 | |

NOTES:

1. Capacitance is characterized but not tested.

2. TA = 25°C, f = 1MHz, VIN = 0V, VOUT = 0V.

PINDESCRIPTION

| Pin Names | I/O | Description | | |
|-----------|-----|--|--|--|
| A, 1B, 2B | I/O | Buses A, 1B, 2B | | |
| SEL0, 1 | Ι | Control Pins for MUX and Switch Enable Functions | | |
| TEST0, 1 | | | | |

FUNCTION TABLE⁽¹⁾

| SEL0 | TEST0 | Description |
|------|-------|-----------------------|
| L | L | 0A to 1B |
| Н | L | 0A to 2B |
| Х | Н | 0A to 1B and 0A to 2B |
| SEL1 | TEST1 | Description |
| L | L | 1A to 1B |
| Н | L | 1A to 2B |
| Х | Н | 1A to 1B and 1A to 2B |

NOTE:

1. H = HIGH Voltage Level L = LOW Voltage Level

X = DOn't Care

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DC ELECTRICAL CHARACTERISTICS OVER OPERATING RANGE

Following Conditions Apply Unless Otherwise Specified:

Industrial: TA = -40° C to $+85^{\circ}$ C, VCC = $5.0V \pm 10\%$

| Symbol | Parameter | Test Conditions ⁽¹⁾ | | Min. | Тур. ⁽²⁾ | Max. | Unit |
|--------|--------------------------------|----------------------------------|--|------|---------------------|------|------|
| Vih | Control Input HIGH Voltage | Guaranteed Logic HIGH for (| Guaranteed Logic HIGH for Control Inputs | | — | _ | V |
| Vil | Control Input LOW Voltage | Guaranteed Logic LOW for C | Guaranteed Logic LOW for Control Inputs | | — | 0.8 | V |
| Ін | Control Input HIGH Current | Vcc = Max. | VI = VCC | - | — | ±1 | μA |
| liL | Control Input LOW Current | | VI = GND | - | — | ±1 | |
| Іоzн | Current During | Vcc = Max., Vo = 0 to 5V | | - | _ | ±1 | μA |
| Iozl | Bus Switch Disconnect | | | — | — | ±1 | |
| νικ | Clamp Diode Voltage | Vcc = Min., IIN = -18mA | | _ | -0.7 | -1.2 | V |
| IOFF | Switch Power Off Leakage | Vcc = 0V, VIN or Vo ≤ 5.5 V | | _ | _ | ±1 | μA |
| lcc | Quiescent Power Supply Current | Vcc = Max., VIN = GND or V | Vcc | — | 0.1 | 3 | μA |

BUS SWITCH IMPEDANCE OVER OPERATING RANGE

 $Following\,Conditions\,Apply\,Unless\,Otherwise\,Specified:$

Industrial: TA = -40° C to $+85^{\circ}$ C, VCC = $5.0V \pm 10\%$

| Symbol | Parameter | Test Conditions | Min. | Тур. ⁽¹⁾ | Max. | Unit |
|--------|--|---------------------------------------|------|---------------------|------|------|
| Ron | Switch On Resistance ⁽²⁾ | Vcc = Min., $Vin = 0V$, $Ion = 12mA$ | — | 5 | 7 | Ω |
| | | Vcc = Min., VIN = 2.4V, ION = 8mA | — | 10 | 15 | |
| los | Short Circuit Current, A to B ⁽³⁾ | A(B) = 0V, B(A) = Vcc | 100 | — | — | mA |

NOTES:

1. Typical values are at Vcc = 5.0V, +25°C ambient.

2. The voltage drop between the indicated ports divided by the current through the switch.

3. Not more than one output should be shorted at one time. Duration of the test should not exceed one second.

POWER SUPPLY CHARACTERISTICS

| Symbol | Parameter | Test Conditions ⁽¹⁾ | | Min. | Тур. ⁽²⁾ | Max. | Unit |
|--------|---|---|-------------------------|------|---------------------|------|-----------------------|
| Δlcc | Quiescent Power Supply Current TTL Inputs HIGH | Vcc = Max. $VIN = 3.4V^{(3)}$ | | — | 0.5 | 1.5 | mA |
| ICCD | Dynamic Power Supply Current ^(4,5) | Vcc = Max. One Select Pin Toggling 50% Duty Cycle | VIN = VCC VIN = GND | _ | 30 | 40 | μΑ/ MHz/ Select |
| ICCD | Dynamic Power Supply Current ^(4,5) | Vcc = Max. One Test Pin Toggling 50% Duty Cycle | Vin = Vcc Vin = GND | _ | 120 | 160 | μΑ/ MHz/ Test |
| lc | Total Power Supply Current ⁽⁶⁾ | Vcc = Max. One Select Pin Toggling | VIN = VCC VIN = GND | - | 0.3 | 0.4 | mA |
| | | fi = 10MHz 50% Duty Cycle | VIN = VCC VIN = 3.4V | - | 0.6 | 1.2 | |
| | | Vcc = Max. Two Select Pins Toggling | VIN = VCC VIN = GND | — | 0.6 | 0.8 | |
| | | fi = 10MHz 50% Duty Cycle | VIN = VCC VIN = 3.4V | _ | 1.1 | 2.3 | |

NOTES:

1. For conditions shown as Max. or Min., use appropriate value specified under Electrical Characteristics for the applicable device type. Ta = -40°C to +85°C

2. Typical values are at Vcc = 5.0V, +25°C ambient.

3. Per TTL driven input (VIN = 3.4V). All other inputs at Vcc or GND. Switch inputs do not contribute to Δ Icc.

4. This parameter represents the current required to switch the internal capacitance of the control inputs at the specified frequency.

Switch inputs generate no significant power supply currents as they transition. This parameter is not directly testable, but is derived for use in Total Power Supply Calculations. 5. CPD = IccD/Vcc

CPD = Power Dissipation Capacitance

6. IC = IQUIESCENT + INPUTS + IDYNAMIC

 $IC = ICC + \Delta ICC DHNT + ICCD (fiN)$

Icc = Quiescent Current

 ΔIcc = Power Supply Current for a TTL High Input (VIN = 3.4V)

DH = Duty Cycle for TTL Inputs High

NT = Number of TTL Inputs at DH

ICCD = Dynamic Current Caused by an Input Transition Pair (HLH or LHL)

fi = Control Input Frequency

N = Number of Control Inputs Toggling at fi

SWITCHING CHARACTERISTICS OVER OPERATING RANGE

Following Conditions Apply Unless Otherwise Specified:

Industrial: TA = -40° C to $+85^{\circ}$ C, VCC = $5.0V \pm 10\%$

| | | | Vcc = 5V ± 10% | þ | Vcc = | = 4V | |
|--------------|--|------|----------------|------|-------|------|------|
| Symbol | Description ⁽¹⁾ | Min. | Тур. | Max. | Min. | Max. | Unit |
| tplh | Data Propagation Delay | _ | _ | 0.25 | _ | 0.25 | ns |
| t PHL | A to B, B to A ⁽²⁾ | | | | | | |
| tвx | Switch Multiplex Delay | 1.5 | _ | 6.5 | _ | 7 | ns |
| | SEL to A | | | | | | |
| tрzн | Switch CONNECT Delay | 1.5 | _ | 6.5 | _ | 7 | ns |
| tPZL | SEL, TEST to B | | | | | | |
| t PHZ | Switch DISCONNECT Delay | 1.5 | — | 7 | _ | 7 | ns |
| t PLZ | SEL, TEST to B | | | | | | |
| Qci | Charge Injection During Switch DISCONNECT | - | 1.5 | — | _ | — | рС |
| | TEST to A or B ⁽³⁾ | | | | | | |
| QDCI | Differential Charge Injection During Multiplexer Switching | _ | 0.5 | _ | _ | _ | рС |
| | SEL to A or B ⁽³⁾ | | | | | | |

NOTES:

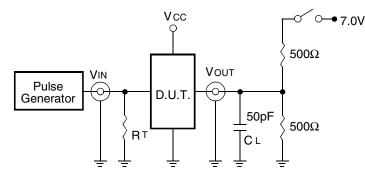
1. See test circuits and waveforms.

2. The bus switch contributes no Propagation Delay other than the RC Delay of the load interacting with the RC of the switch.

3. |Qci| is the charge injection for a single switch DISCONNECT and applies to either single switches or multiplexers. |Qcci| is the charge injection for a multiplexer as the multiplexed port switches from one path to another. Charge injection is reduced because the injection from the DISCONNECT of the first path is compensated by the CONNECT of the second path.

IDT74FST163233 16-BIT2:1 MUX/DEMUX SWITCH

TEST CIRCUITS AND WAVEFORMS



Test Circuits for All Outputs

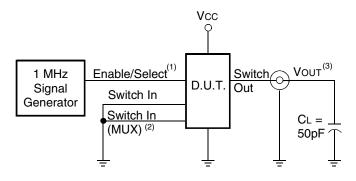
SWITCH POSITION

| Test | Switch |
|---|--------|
| Open Drain Disable Low Enable Low | Closed |
| All Other Tests | Open |

DEFINITIONS:

CL = Load capacitance: includes jig and probe capacitance.

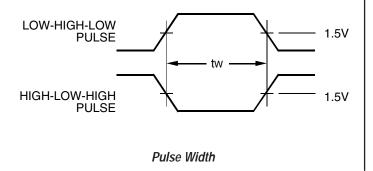
RT = Termination resistance: should be equal to ZOUT of the Pulse Generator.



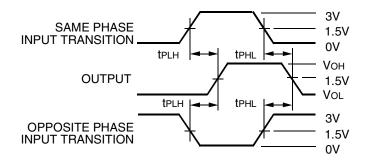
Charge Injection

NOTES:

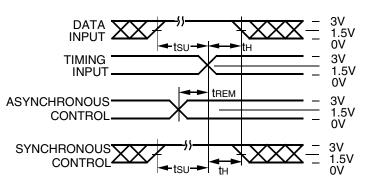
- 1. Select is used with multiplexers for measuring IQDCII during multiplexer select. During all other tests Enable is used.
- 2. Used with multiplexers to measure IQDCII only.
- 3. Charge Injection = $\Delta Vou\tau CL$, with Enable toggling for IQcII or Select toggling for IQDCII. $\Delta Vou\tau$ is the change in Vout and is measured with a 10M Ω probe.



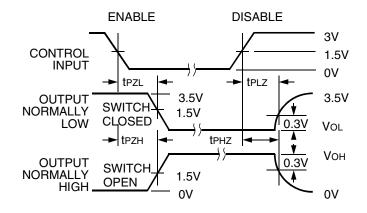
INDUSTRIAL TEMPERATURE RANGE



Propagation Delay



Set-up, Hold, and Release Times

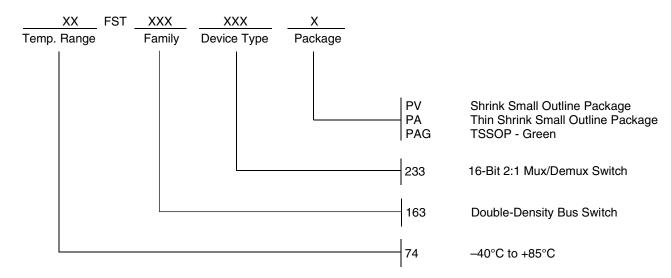


Enable and Disable Times

NOTES:

- 1. Diagram shown for input Control Enable-LOW and input Control Disable-HIGH.
- 2. Pulse Generator for All Pulses: Rate \leq 1.0MHz; tF \leq 2.5ns; tR \leq 2.5ns.

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